

March 2021

© Diodes Incorporated

DUAL N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	Rds(on) Max	I _D Max T _A = +25°C
	2.4Ω @ V _{GS} = 10V	510mA
60V	4.0Ω @ V _{GS} = 4V	390mA

Features and Benefits

- Low On-Resistance
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- ESD Protected Up To 2kV
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative.

https://www.diodes.com/quality/product-definitions/

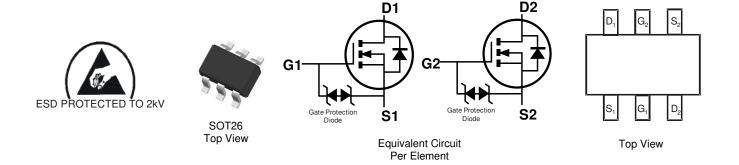
Description and Applications

This new generation MOSFET is designed to minimize the on-state resistance (RDS(ON)) yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

- DC-DC Converters
- Power Management Functions
- Analog Switch

Mechanical Data

- Case: SOT26
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (§3)
- Weight: 0.015 grams (Approximate)



Ordering Information (Note 4)

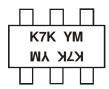
Part Number	Case	Packaging
DMN601DMK-7	SOT26	3,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.



Marking Information



K7K = Marking Code YM = Date Code Marking Y or \overline{Y} = Year (ex: I = 2021) M = Month (ex: 9 = September)

Date Code Key

Year	2005		2021	2022	2023	2024	2025	2026	2027	2028	2029	2030
Code	S			J	K	L	М	N	0	Р	R	S
Month	lan	Eob	Mar	Anr	May	lun	lul	Aug	Son	Oct	Nov	Doo
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec

Maximum Ratings (@ $T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage	V _{DSS}	60	V		
Gate-Source Voltage			V_{GSS}	±20	V
Continuous Dusin Comment (Nata C) (V 10)()	Steady State	T _A = +25°C T _A = +70°C	lD	510 400	mA
Continuous Drain Current (Note 6) (V _{GS} = 10V)	lD	580 470	mA		
Continuous Dusin Courset (Note C) (V 4)()	lD	390 300	mA		
Continuous Drain Current (Note 6) (V _{GS} = 4V)	I _D	440 340	mA		
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%	I _{DM}	850	mA		
Maximum Body Diode Continuous Current	Is	510	mA		

Thermal Characteristics

Characteristic		Symbol	Value	Unit	
Total Power Dissipation (Note 5)		PD	0.7	W	
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	Reja	157	°C/W	
Thermal nesistance, Junction to Ambient (Note 5)	t<10s	MθJA	121	C/VV	
Total Power Dissipation (Note 6)		PD	0.98	W	
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	Da	113		
Thermal nesistance, Junction to Ambient (Note 6)	t<10s	$R_{\theta JA}$	88	°C/W	
Thermal Resistance, Junction to Case (Note 6)		Rejc	26		
Operating and Storage Temperature Range		TJ, TSTG	-55 to +150	°C	

Notes:

^{5.} Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.6. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.



Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

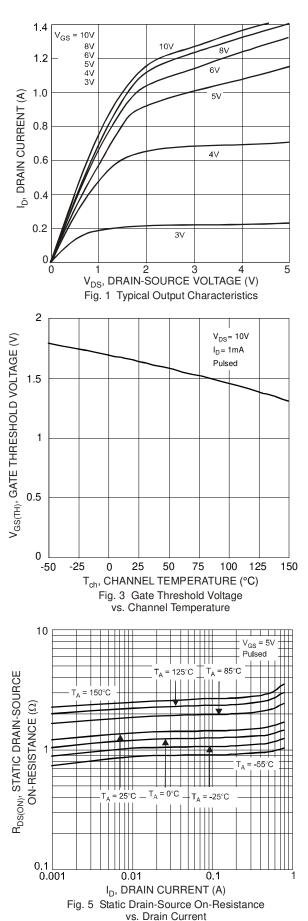
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BVDSS	60	_	_	٧	$V_{GS} = 0V$, $I_D = 10\mu A$	
Zero Gate Voltage Drain Current	IDSS		_	1	μΑ	$V_{DS} = 60V$, $V_{GS} = 0V$	
Gate-Source Leakage	IGSS		_	±10	μΑ	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V _{GS(TH)}	1.0	1.6	2.5	>	$V_{DS} = 10V$, $I_D = 1mA$	
Static Drain-Source On-Resistance	Dagger		1.2	2.4	Ω	$V_{GS} = 10V, I_D = 200mA$	
Static Dialif-Source Off-Resistance	Rds(on)		1.5	4.0	32	$V_{GS} = 4V, I_D = 200mA$	
Forward Transfer Admittance	Y _{fs}	100		_	mS	$V_{DS} = 10V, I_D = 200mA$	
Diode Forward Voltage	V _{SD}	0.5	0.8	1.4	V	$V_{GS} = 0V, I_{S} = 115mA$	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	Ciss		30	50	рF	V 05V V 0V	
Output Capacitance	Coss	_	5	25	рF	V _{DS} = 25V, V _{GS} = 0V f = 1.0MHz	
Reverse Transfer Capacitance	Crss		3	5	рF	1 - 1.000112	
Gate Resistance	Rg		133	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge	Qg		304	_		V 45V V 40V	
Gate-Source Charge	Q _{gs}	_	84	_	рC	$V_{GS} = 4.5V, V_{DS} = 10V,$	
Gate-Drain Charge	Qgd	_	203	_		I _D = 250mA	
Turn-On Delay Time	t _{D(ON)}	_	3.9	_			
Turn-On Rise Time	tR	_	3.4		no	$V_{DS} = 30V, I_{D} = 0.2A,$ $V_{GS} = 10V, R_{G} = 25\Omega, R_{L} = 150\Omega$	
Turn-Off Delay Time	tD(OFF)	_	15.7	_	ns		
Turn-Off Fall Time	tF	_	9.9	_			

Notes:

^{7.} Short duration pulse test used to minimize self-heating effect.

^{8.} Guaranteed by design. Not subject to production testing.





1.00

V_{DS} = 10V
Pulsed

T_A = 125°C

T_A = 75°C

T_A = 25°C

V_{GS}, GATE-SOURCE VOLTAGE (V)
Fig. 2 Typical Transfer Characteristics

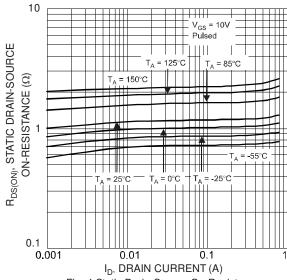


Fig. 4 Static Drain-Source On-Resistance vs. Drain Current

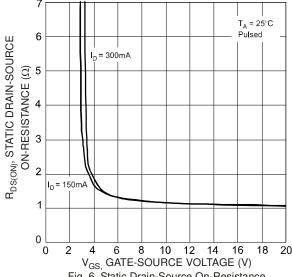


Fig. 6 Static Drain-Source On-Resistance vs. Gate-Source Voltage



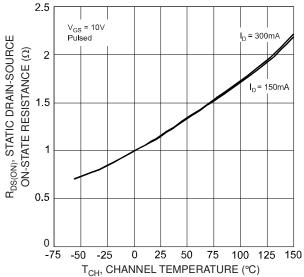


Fig. 7 Static Drain-Source On-State Resistance vs. Channel Temperature

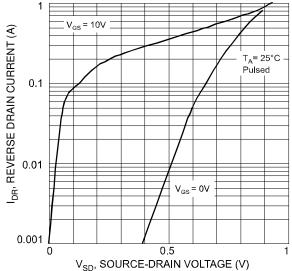


Fig. 9 Reverse Drain Current vs. Source-Drain Voltage

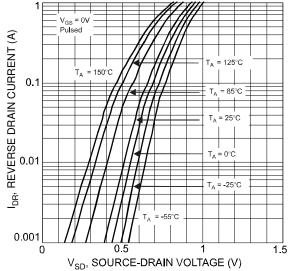


Fig. 8 Reverse Drain Current vs. Source-Drain Voltage

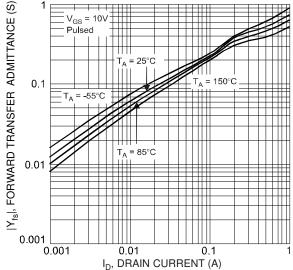
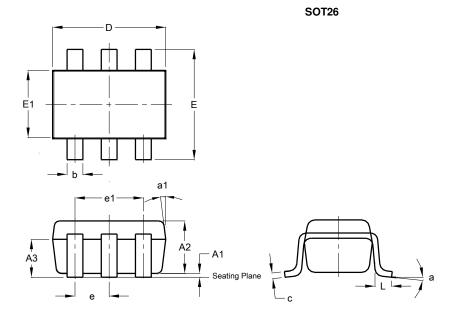


Fig.10 Forward Transfer Admittance vs. Drain Current



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

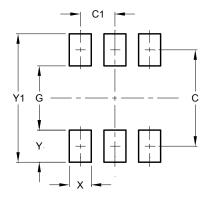


SOT26							
Dim	Min	Max	Тур				
A 1	0.013	0.10	0.05				
A2	1.00	1.30	1.10				
A3	0.70	0.80	0.75				
b	0.35	0.50	0.38				
С	0.10	0.20	0.15				
D	2.90 3.10		3.00				
е	-	-	0.95				
e1			1.90				
Е	2.70 3.00		2.80				
E1	1.50 1.70		1.60				
L	0.35 0.55		0.40				
а	-	-	8°				
a1	-	-	7°				
All Dimensions in mm							

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT26



Dimensions	Value (in mm)
С	2.40
C1	0.95
G	1.60
Х	0.55
Y	0.80
Y1	3.20



IMPORTANT NOTICE

- 1. DIODES INCORPORATED AND ITS SUBSIDIARIES ("DIODES") MAKE NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO ANY INFORMATION CONTAINED IN THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).
- 2. The Information contained herein is for informational purpose only and is provided only to illustrate the operation of Diodes products described herein and application examples. Diodes does not assume any liability arising out of the application or use of this document or any product described herein. This document is intended for skilled and technically trained engineering customers and users who design with Diodes products. Diodes products may be used to facilitate safety-related applications; however, in all instances customers and users are responsible for (a) selecting the appropriate Diodes products for their applications, (b) evaluating the suitability of the Diodes products for their intended applications, (c) ensuring their applications, which incorporate Diodes products, comply the applicable legal and regulatory requirements as well as safety and functional-safety related standards, and (d) ensuring they design with appropriate safeguards (including testing, validation, quality control techniques, redundancy, malfunction prevention, and appropriate treatment for aging degradation) to minimize the risks associated with their applications.
- 3. Diodes assumes no liability for any application-related information, support, assistance or feedback that may be provided by Diodes from time to time. Any customer or user of this document or products described herein will assume all risks and liabilities associated with such use, and will hold Diodes and all companies whose products are represented herein or on Diodes' websites, harmless against all damages and liabilities.
- 4. Products described herein may be covered by one or more United States, international or foreign patents and pending patent applications. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks and trademark applications. Diodes does not convey any license under any of its intellectual property rights or the rights of any third parties (including third parties whose products and services may be described in this document or on Diodes' website) under this document.
- 5. Diodes products are provided subject to Diodes' Standard Terms and Conditions of Sale (https://www.diodes.com/about/company/terms-and-conditions/terms-and-conditions-of-sales/) or other applicable terms. This document does not alter or expand the applicable warranties provided by Diodes. Diodes does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel.
- 6. Diodes products and technology may not be used for or incorporated into any products or systems whose manufacture, use or sale is prohibited under any applicable laws and regulations. Should customers or users use Diodes products in contravention of any applicable laws or regulations, or for any unintended or unauthorized application, customers and users will (a) be solely responsible for any damages, losses or penalties arising in connection therewith or as a result thereof, and (b) indemnify and hold Diodes and its representatives and agents harmless against any and all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim relating to any noncompliance with the applicable laws and regulations, as well as any unintended or unauthorized application.
- 7. While efforts have been made to ensure the information contained in this document is accurate, complete and current, it may contain technical inaccuracies, omissions and typographical errors. Diodes does not warrant that information contained in this document is error-free and Diodes is under no obligation to update or otherwise correct this information. Notwithstanding the foregoing, Diodes reserves the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. This document is written in English but may be translated into multiple languages for reference. Only the English version of this document is the final and determinative format released by Diodes.
- 8. Any unauthorized copying, modification, distribution, transmission, display or other use of this document (or any portion hereof) is prohibited. Diodes assumes no responsibility for any losses incurred by the customers or users or any third parties arising from any such unauthorized use.

Copyright © 2021 Diodes Incorporated

www.diodes.com